

REMARKS

Claims 1, 3, 4, 6, 7, 9, 10 and 12 are pending in this application. By this Amendment, claims 1 and 7 are amended. Reconsideration of the application in view of the Amendments and the following Remarks is respectfully requested.

I. Rejection Under 35 U.S.C. §112, Second Paragraph

Claims 1, 3, 4, 6, 7, 9, 10 and 12 are rejected 35 U.S.C. §112, second paragraph as being indefinite. Claims 1, 6 and 7 have been amended to obviate the rejection. Accordingly, withdraw of the rejection under 35 U.S.C. §112, second paragraph is respectfully requested.

II. Rejection Under 35 U.S.C. §102(b)

Claims 1, 3, 4, 6, 7, 9, 10 and 12 stand rejected under 35 U.S.C. §102(b) as being anticipated by Thompson (U.S. Patent No. 5,293,067). The rejection is respectfully traverse.

In particular, Thompson fails to disclose or suggest a substrate for semiconductor apparatus including at least one contour line formed on at least one surface of the substrate main body, the contour line defining an area on the substrate main body, portions of the plurality of leads extend into the area defined by the contour line, and through-holes are arranged corresponding to the respective leads, such that each lead has a through-hole in an area other than the area defined by the contour line and through-hole in the area defined by the contour line, wherein when the substrate main body is cut along the contour line, the portions of the plurality of leads in the area defined by the contour line and the through-holes connected to the portion of the perspective plurality of leads define the conduction sections, as recited in independent claim 1, and similarly recited in independent claim 7.

Thompson instead disclose an integrated circuit chip carrier assembly including a semiconductor device 10 carried to a circuitry pattern 18 on a first side of the circuit carrying

substrate 16. The substrate also contains other circuitry 20 that interconnects pad to the conductive through-holes of vias 22 in the substrate.

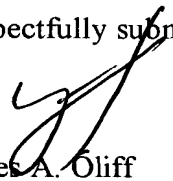
However, Thompson does not disclose or suggest the through-holes are arranged corresponding to respective leads such that each lead has a through-hole in an area other than the area defined by the contour line and a through-hole in the area defined by the contour line, wherein when the substrate main body is cut along the contour line, the remaining portions of the plurality of leads in the area defined by the contour line and the through-holes connected to the portions of the respective plurality of leads define a conduction sections.

Accordingly, claims 1, 3-4, 6-7 and 9-12 define patentable subject matter.

Accordingly, favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,


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